



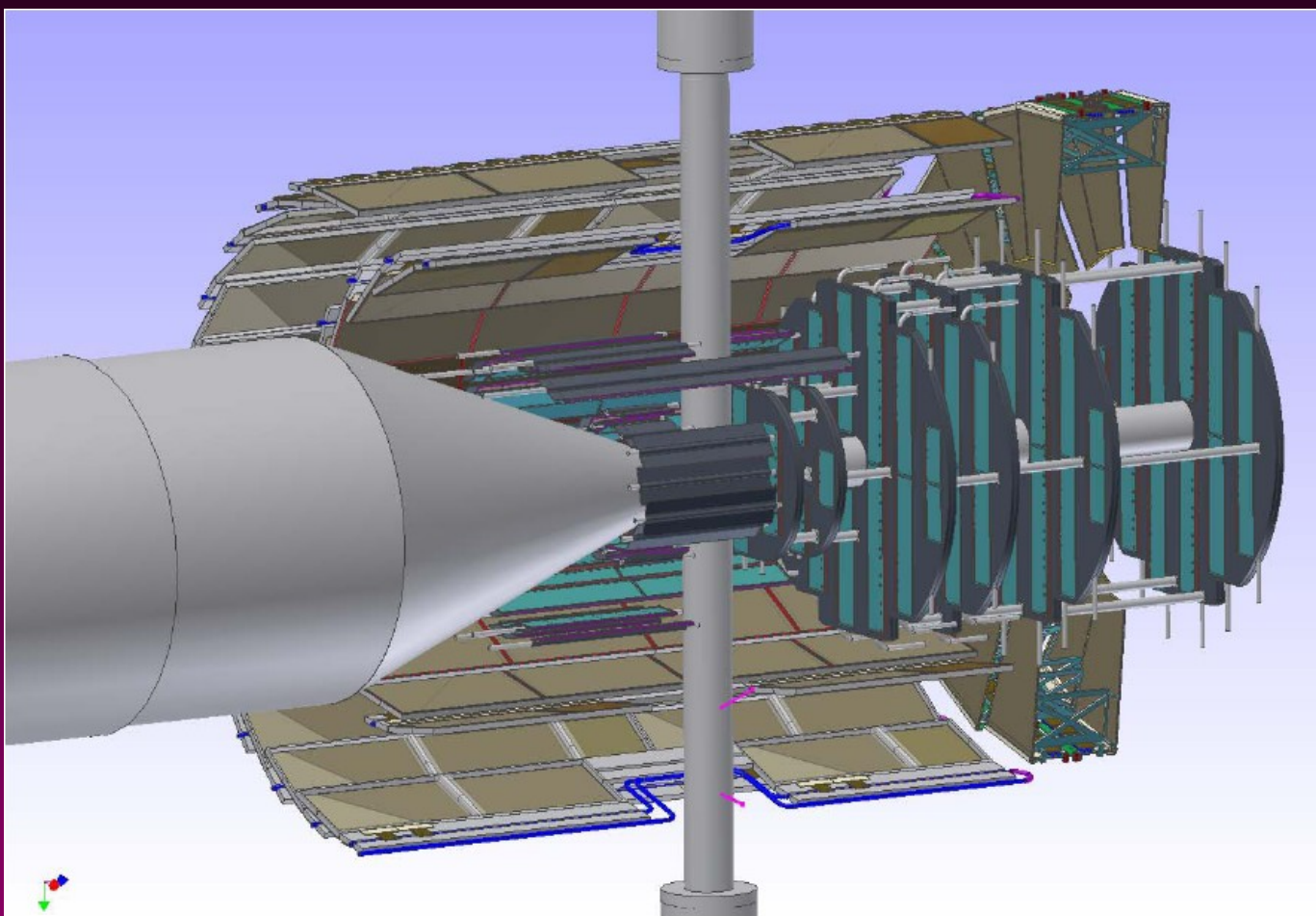
Pixel Detector



Sezione di Torino

MVD silicon pixel detector : readout architecture and ASIC developments

*D. Calvo, P. De Remigis, T. Kughatasan,
G. Mazza, A. Rivetti, L. Toscano, R. Wheadon*



* Barrel :

Layer 1 : radius 28 mm, SPDs

Layer 2 : radius 53 mm, SPDs

Layer 3 : radius 92 mm, SSDs

Layer 4 : radius 120 mm, SSDs

* Forward :

Disks 1-2 : radius 37.5 mm,
SPDs

Disks 3-4 : radius 75 mm, SPDs

Disks 5-6 : radius 130 mm,
SPDs + SSDs



Pixel specifications



Sezione di Torino

Pixel size	$100 \times 100 \mu\text{m}^2$
Chip active area	$11.4 \times 11.6 \text{ mm}^2$ (116 rows, 110 cols)
dE/dx measurement	ToT, 12 bits dynamic range
Max input charge	50 fC
Noise floor	$< 32 \text{ aC}$ (200 e^-)
Clock frequency	156.25 MHz
Time resolution	6.4 ns (1.85 ns <i>r.m.s.</i>)
Power consumption	$< 500 \text{ mW/cm}^2$
Max event rate	$6.1 \cdot 10^6 \text{ hits/(cm}^2 \cdot \text{s)}$
Total ionizing dose	$< 100 \text{ kGy}$



Data rates



Sezione di Torino

antiproton-	proton	Ar	Au
Average flux [hits/cm ² ·s] Disk number	$8.24 \cdot 10^5$ Disk 6	$3.30 \cdot 10^5$ Disk 5	$9.47 \cdot 10^4$ Disk 4
Average flux [hits/cm ² ·s] Barrel 1 - stave		$2.55 \cdot 10^5$ stave 3	$1.03 \cdot 10^5$ stave 13
Average flux [hits/cm ² ·s] Barrel 2 - stave		$2.55 \cdot 10^5$ stave 19	$2.54 \cdot 10^4$ stave 25
Max flux [hits/cm ² ·s] [hits/(readout chips·s)]	$6.1 \cdot 10^6$ $\sim 8.1 \cdot 10^6$	$6.8 \cdot 10^5$ $\sim 9 \cdot 10^5$	$1.65 \cdot 10^4$ $\sim 2.18 \cdot 10^4$

p : $2.0 \cdot 10^{32}$

Ar : $2.4 \cdot 10^{31}$

Au : $2.2 \cdot 10^{30}$

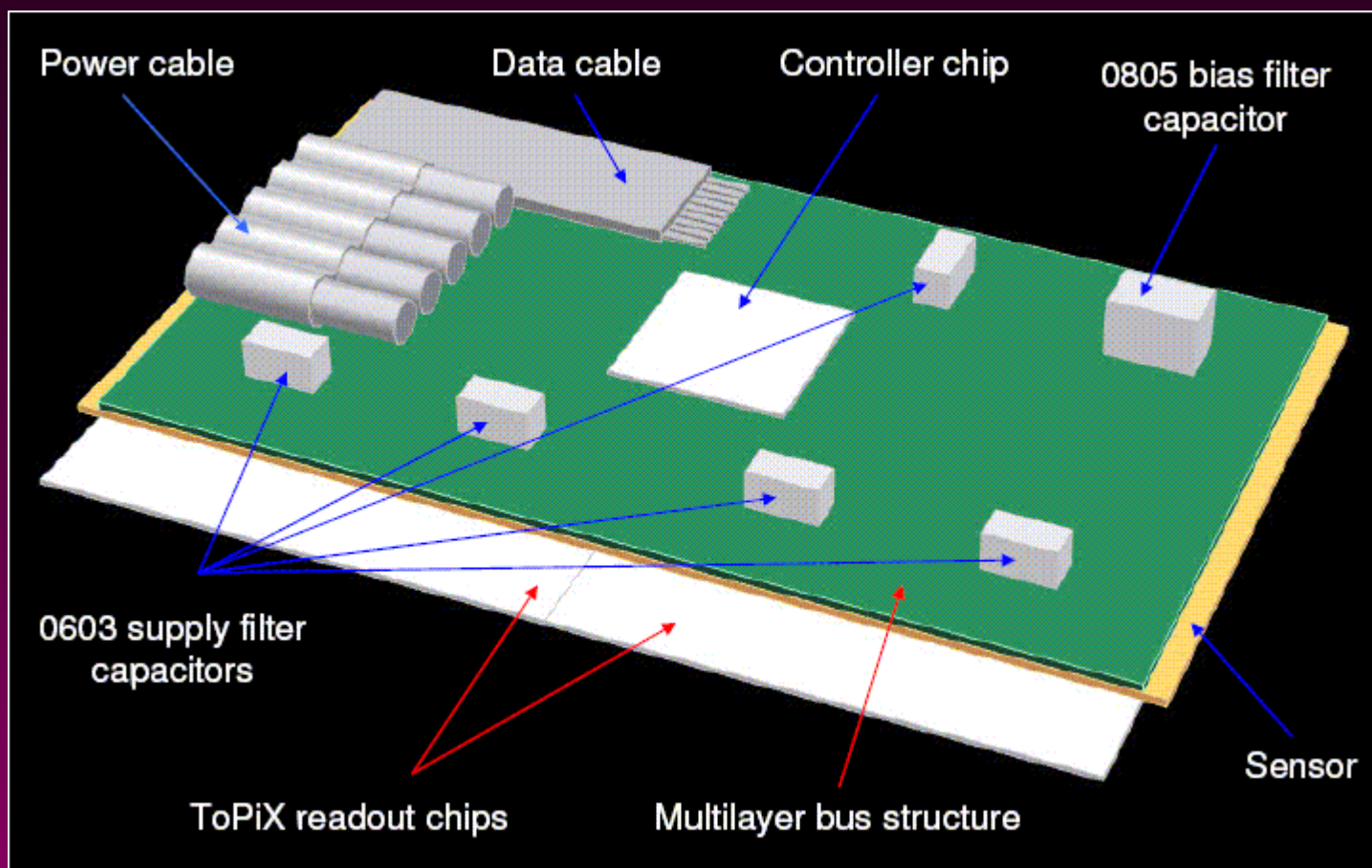
annh. rate $2 \cdot 10^7$ @ 15 GeV/c

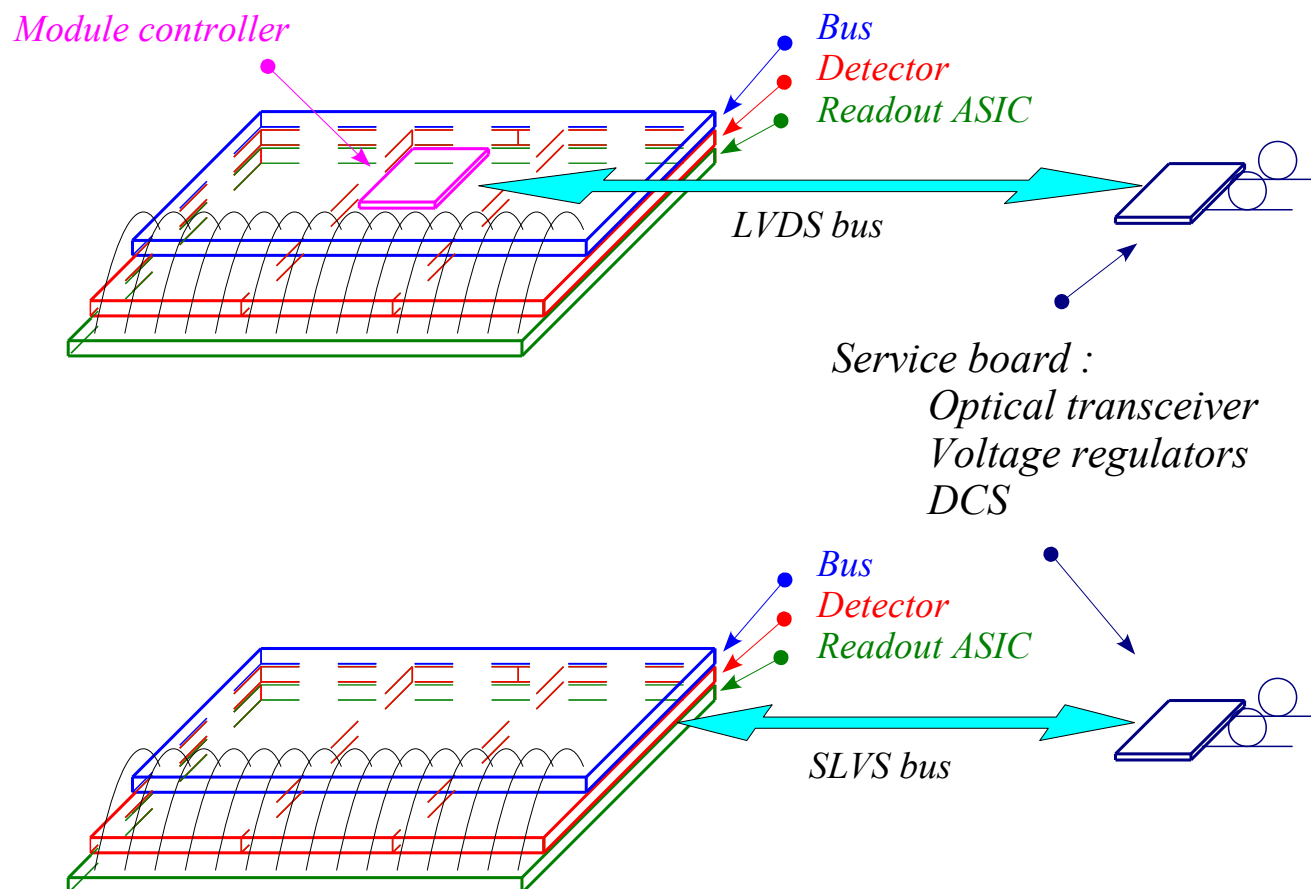


Module concept



Sezione di Torino





Option 1

Option 2



Options pro/cons



Sezione di Torino

* Option 1

- ☺ reduced number of cables
- ☺ simpler ToPiX control logic
- ☺ better management of data rate increase
- ☹ requires an extra chip

* Option 2

- ☺ no need of an extra chip
- ☺ interface already under development at CERN
- ☹ more cables



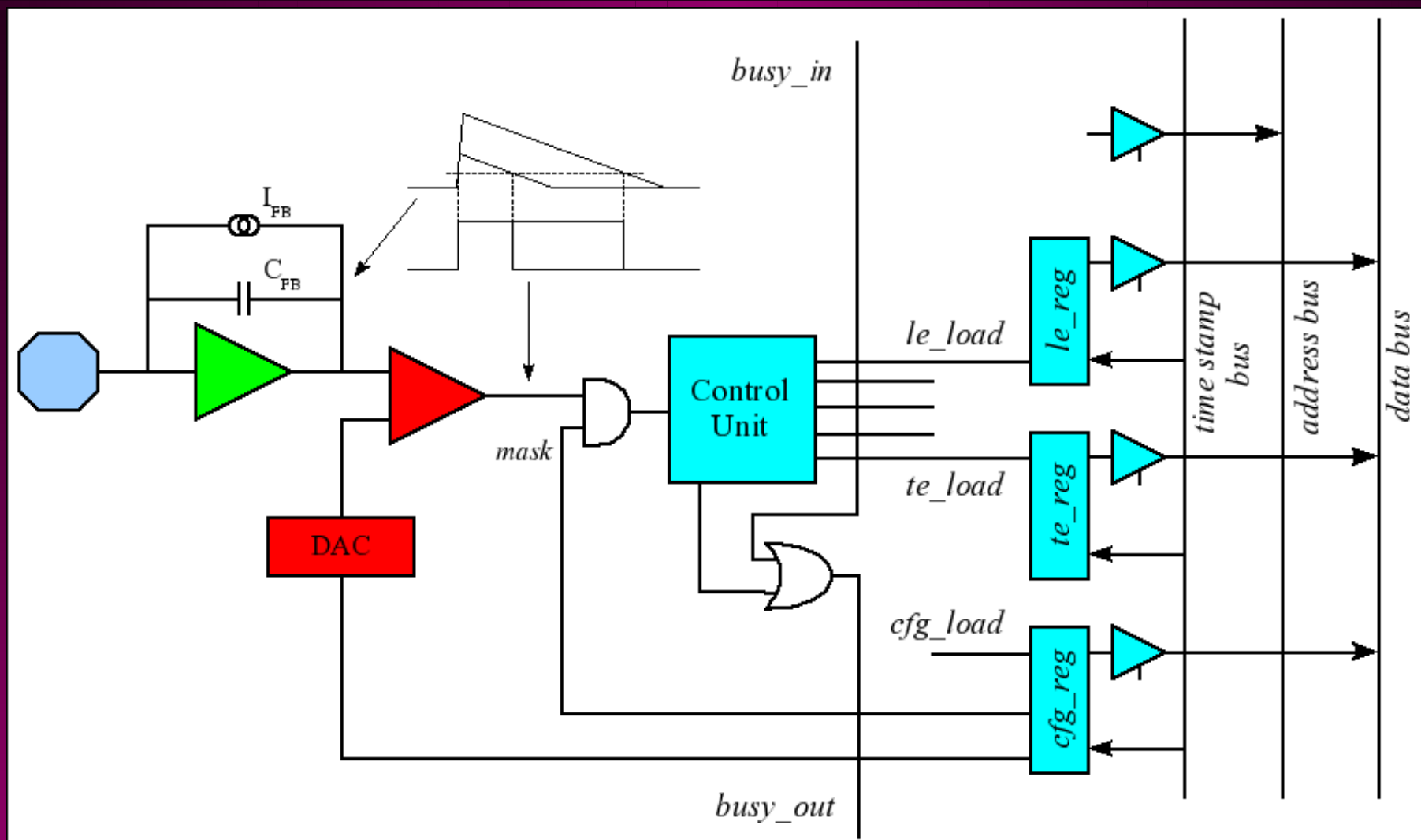
ToPiX ASIC



Sezione di Torino

- * Custom development for the PANDA MVD
- * Provides spatial and time coordinates plus energy resolution measurement (via ToT)
- * Compatible either with p-type or n-type detectors
- * Self triggered architecture
- * Each event has a 12 bits time reference
- * Data corresponding to a 12 bits counter cycle ($26.21 \mu\text{s}$) are packed in a frame, with an 8 bits frame counter (6.71 ms cycle)
- * *Possible modification : counter cycle stopped at 3000 ($19.2 \mu\text{s}$, i.e. 8 bursts) - 8 bits frame counter cycle $\sim 4.9 \text{ ms}$ (8 super-bursts)*

Pixel cell

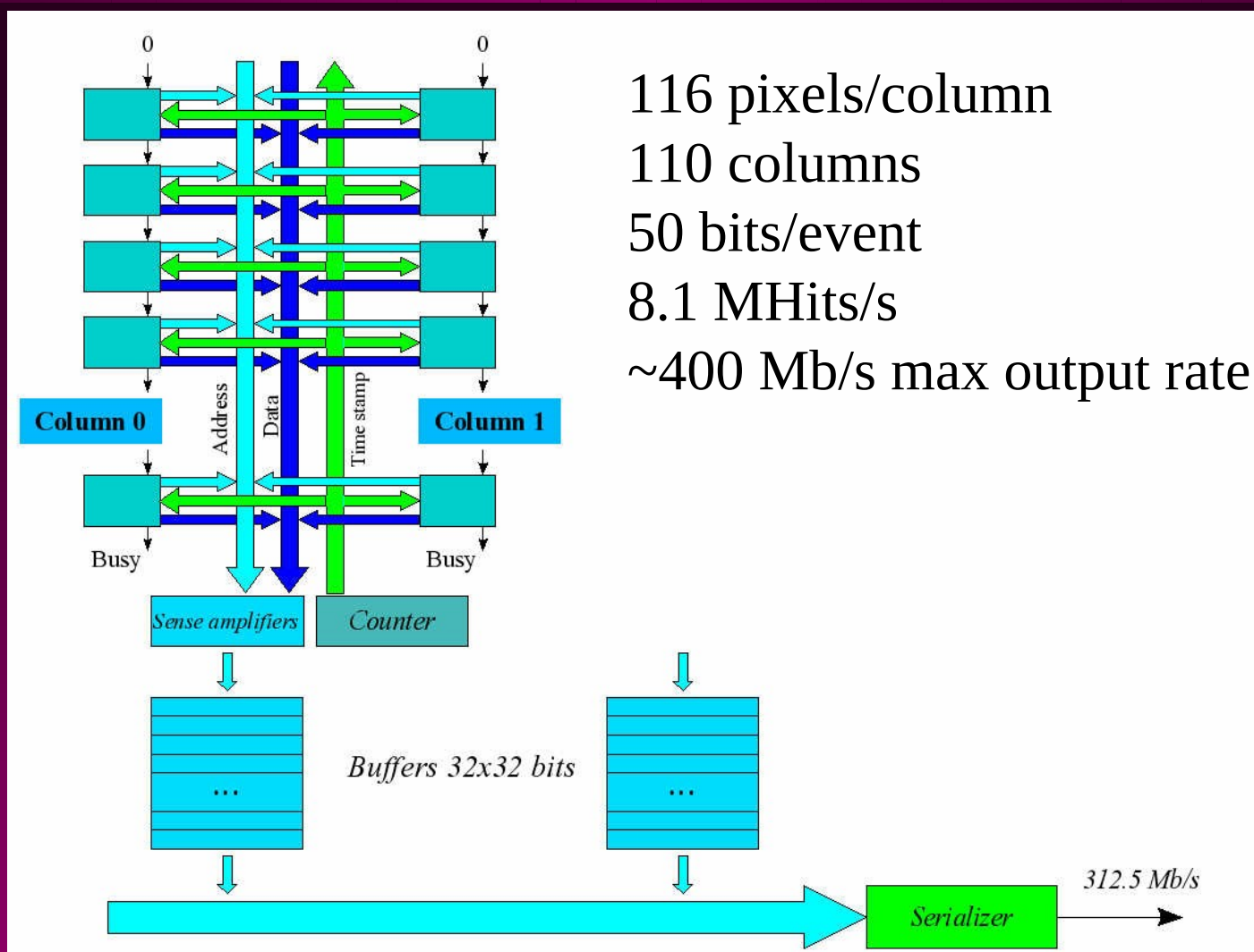




ToPiX block diagram



Sezione di Torino

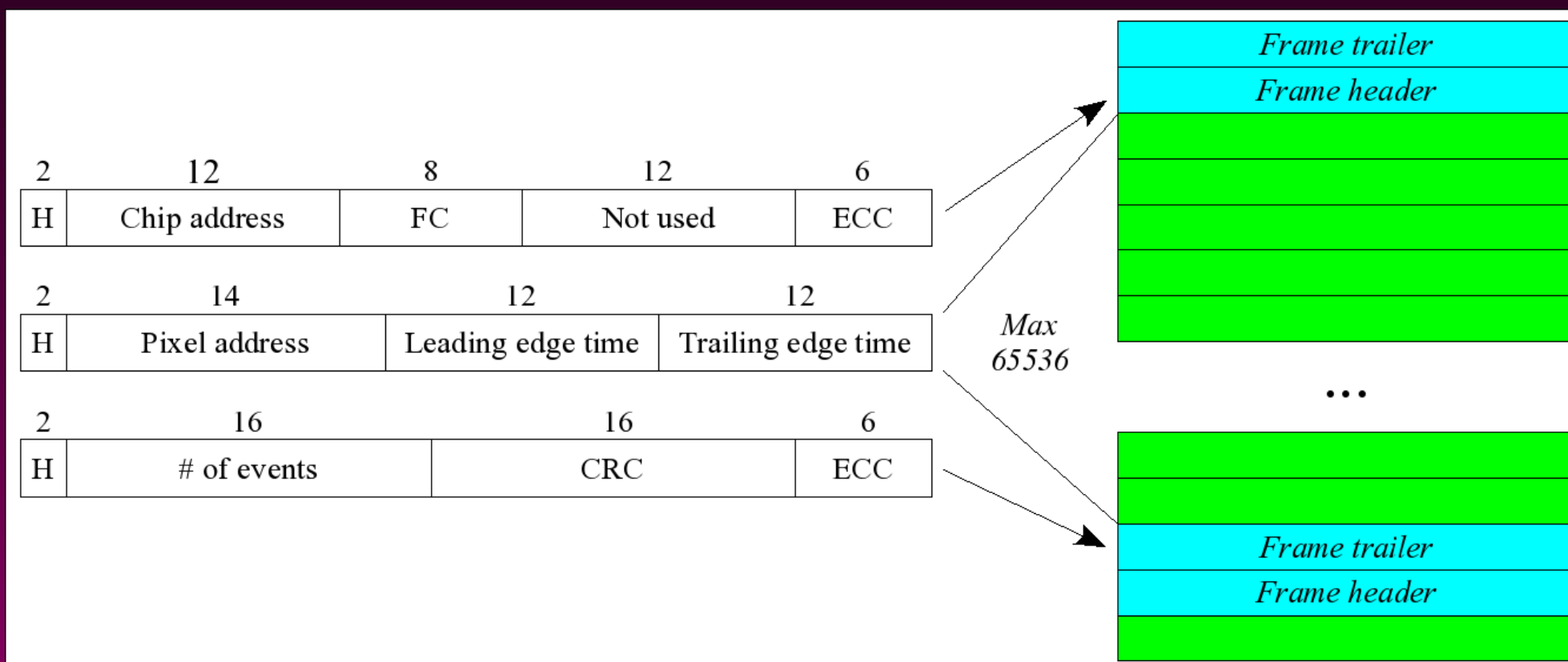


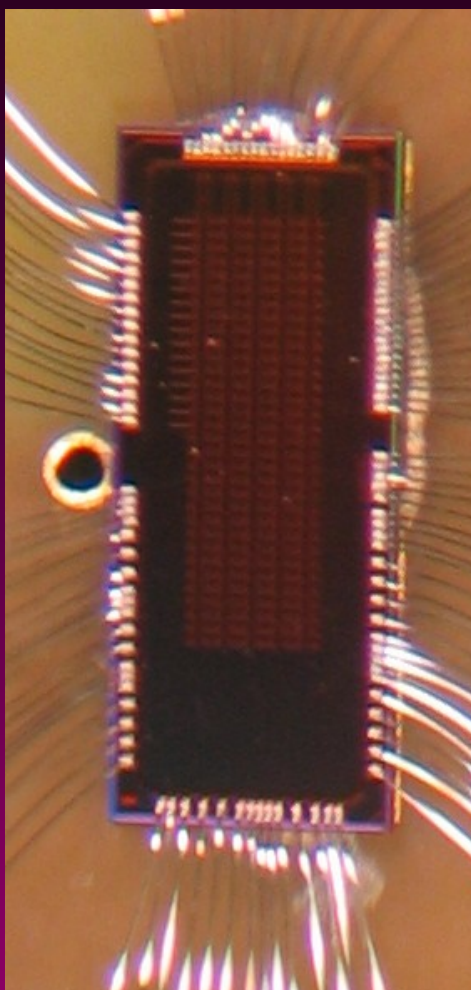


Data format



Sezione di Torino





- Full pixel cell (analogue + digital)
- Two folded columns with 128 cells
- Two columns with 32 cells
- 5x2 mm² die area
- CMOS 0.13 μm LM technology
- Dice-based SEU resistant FFs
- Tests :
 - test bench
 - with a sensor and a radiation source
 - TID and SEU



ToPiX v3



Sezione di Torino

- Under design
- 5x4 mm² die area
- CMOS 0.13 μ m DM technology
 - LM $\rightarrow$ 6 thin, 2 thick metal layers
 - DM $\rightarrow$ 3 thin, 2 thick, 3 RF metal layers
- Triple redundancy-based SEU protection
- End of column logic
- 312.5 Mb/s serial output
- Pads for bump bonding

Topix3 stability with $C_f = 12\text{fF}$

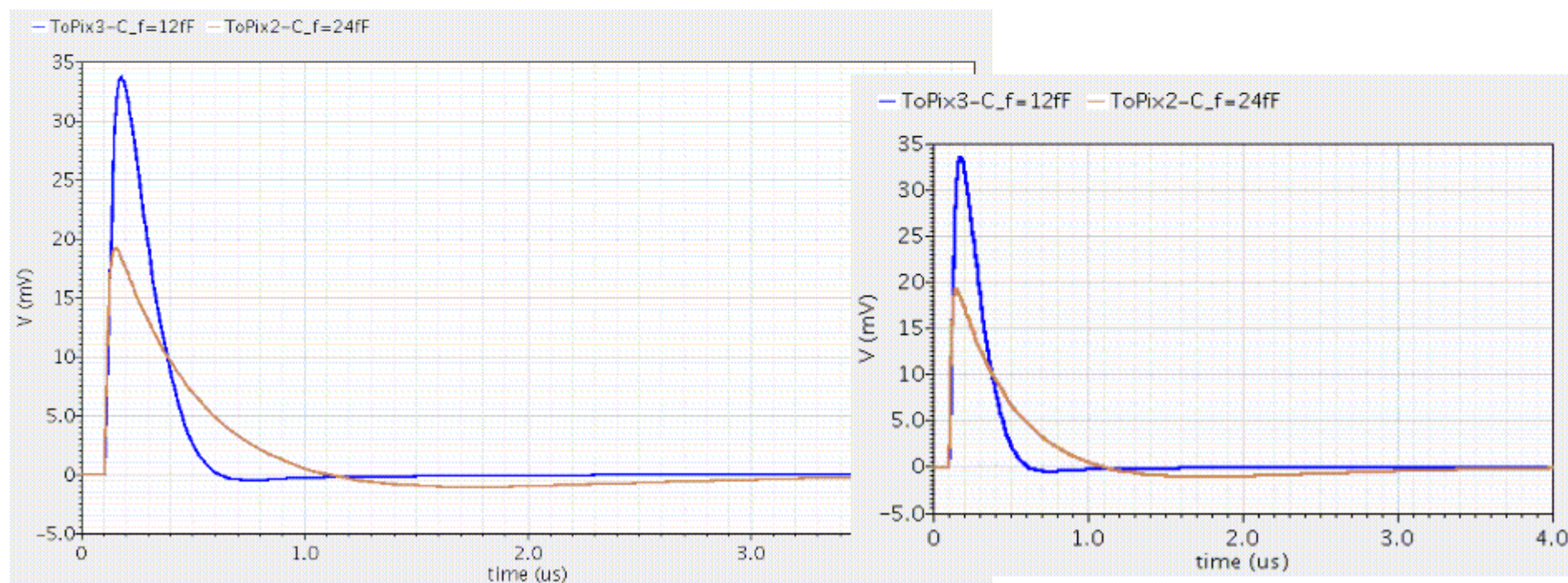
Reduction of the offset in the charge measurement.

The offset in the charge measurement is caused by the channel-to-channel baseline variation:

$$\Delta Q_{offset} = \frac{\Delta V_{var}}{CSA_{gain}} = \Delta V_{var} C_f$$

The ToPix2 value of C_f is 24fF and was chosen as a compromise between gain and stability of the loop.

The number and size of the transistors in the feedback path have been carefully optimized to allow a reduction of the feedback capacitance to 12fF.



T. Kughatasan

Monte Carlo simulation for mismatch and process variation (ToPix3)

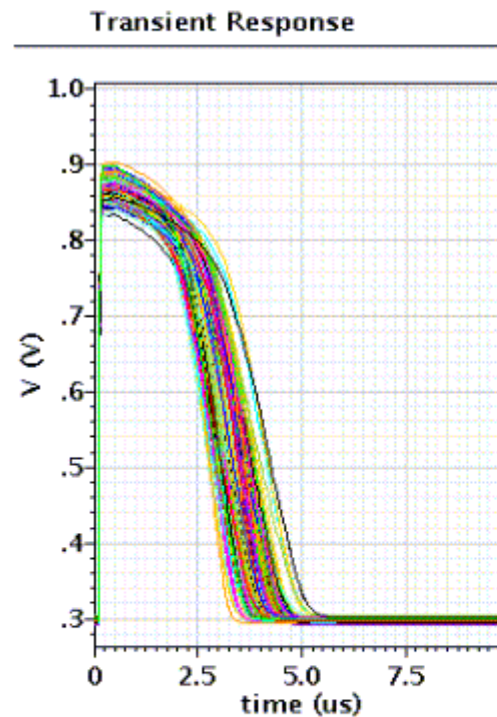
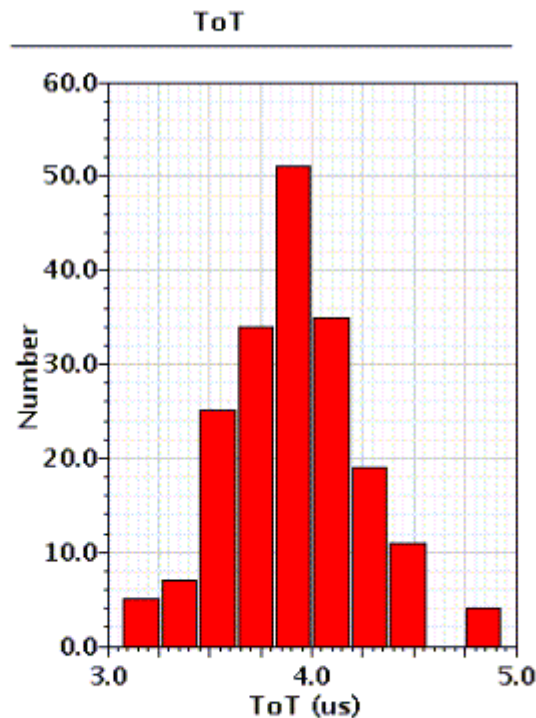
The mismatch effects have been minimized achieving a ToT channel-to-channel variation $\sigma_{\text{ToT}}/\text{ToT}$ of 10%.

Number of simulations = 200

$Q_{in} = 20fC$

Mean = $3.908\mu s$

Standard deviation = $319ns$

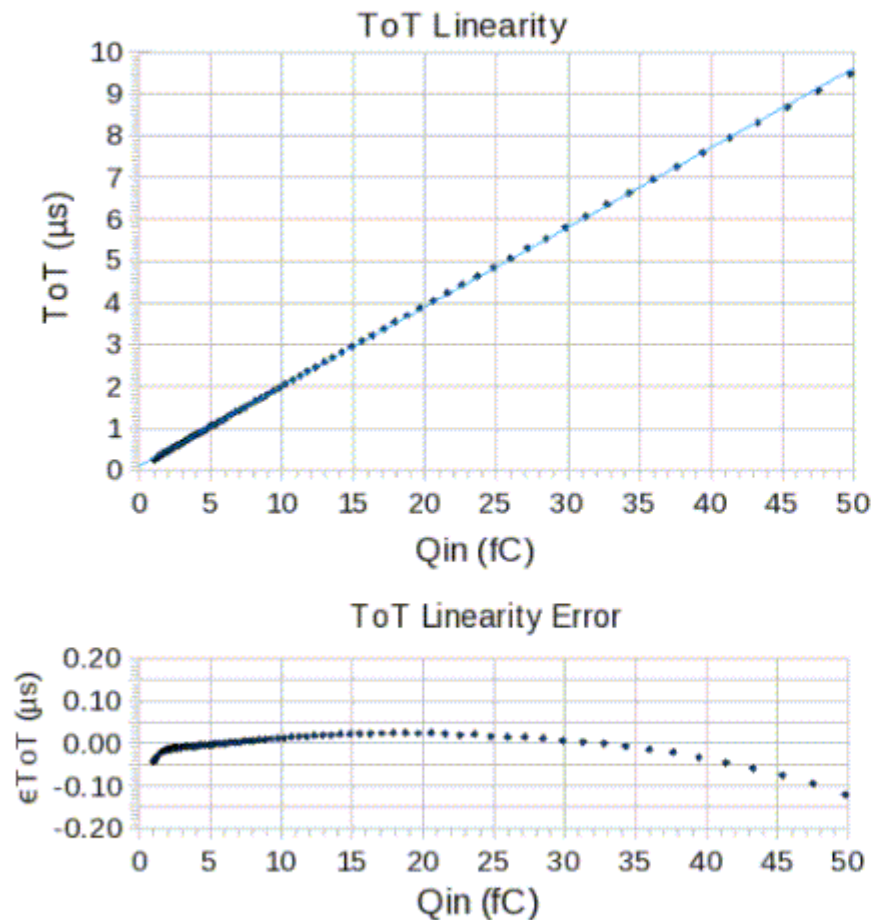


Baseline variation

$$\Delta V_{var} \approx 10mV$$

T. Kughatasan

ToT vs Qin linearity up to 50fC



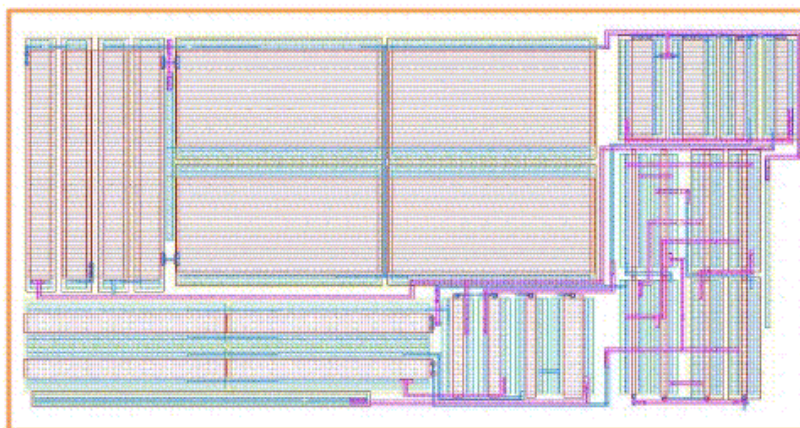
$$ToT[Q_{in}] = 191 \frac{ns}{fC} \cdot Q_{in} + 97 fC$$

Analog Gain	~70mV/fC
Dynamic Range	50 fC
Equivalent Noise Charge	200 e ⁻ rms
Leakage	Up to 50nA
σToT/ToT	10%
Baseline variation	±10mV
Input signal polarity	Selectable
Discharging current	5nA

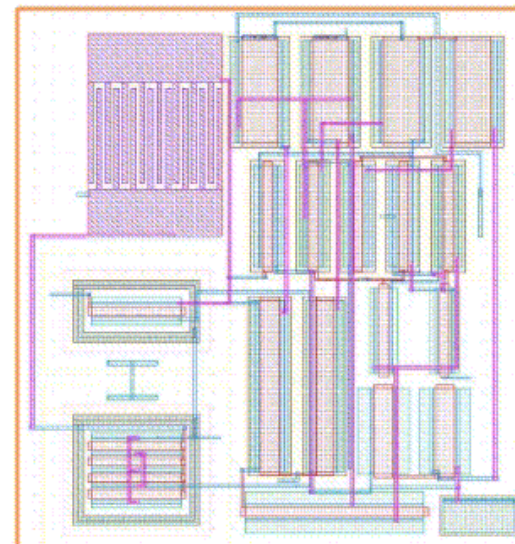
T. Kughatasan

Pixel layout - 1

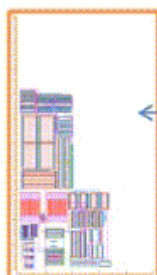
Filter stage: $40\mu\text{m} \times 20\mu\text{m}$ (50% of area of the previous)



Preamplifier $35\mu\text{m} \times 30\mu\text{m}$



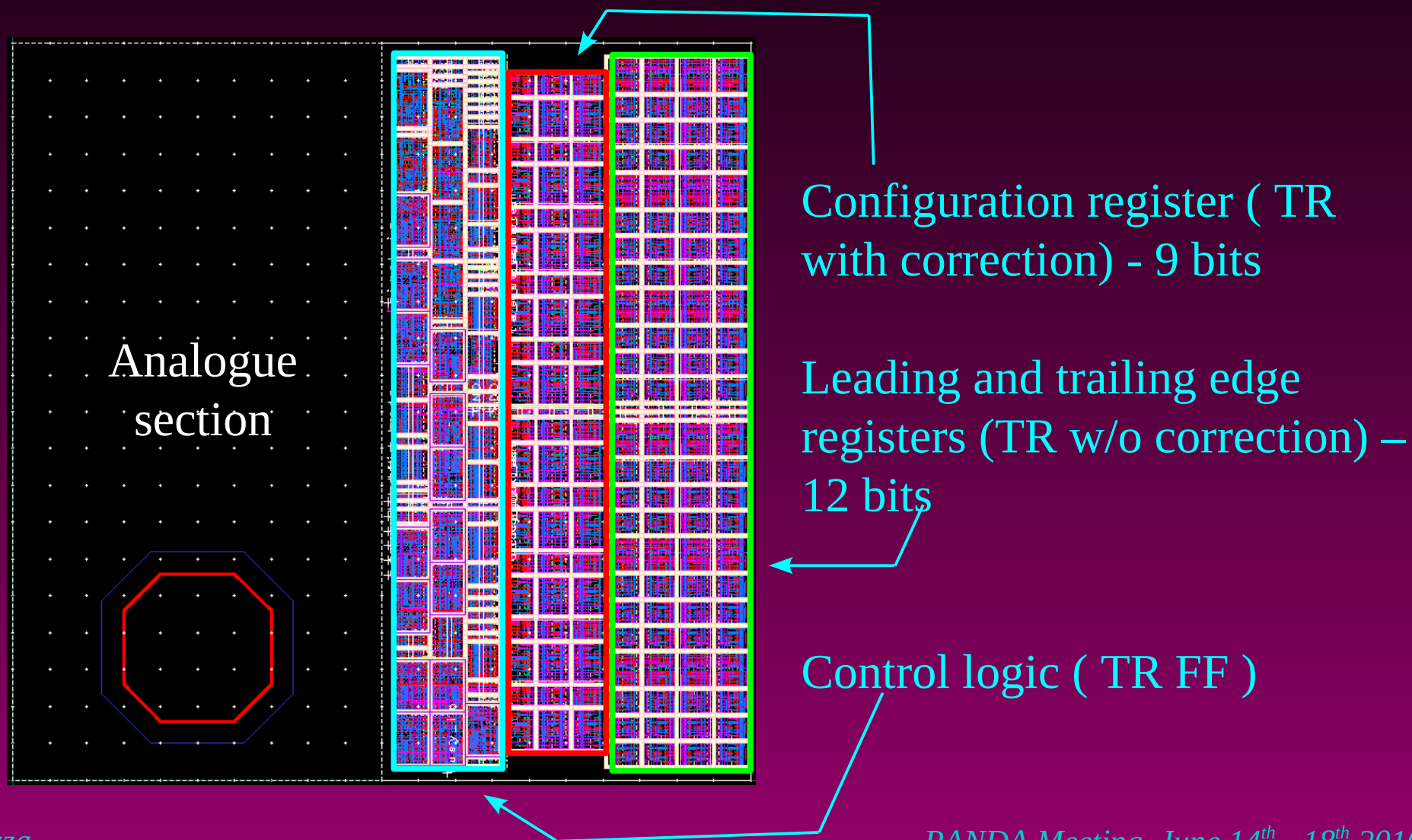
Analog Cell $100\mu\text{m} \times 50\mu\text{m}$ (-30%)



← To be designed

T. Kughatasan

Pixel layout - 2

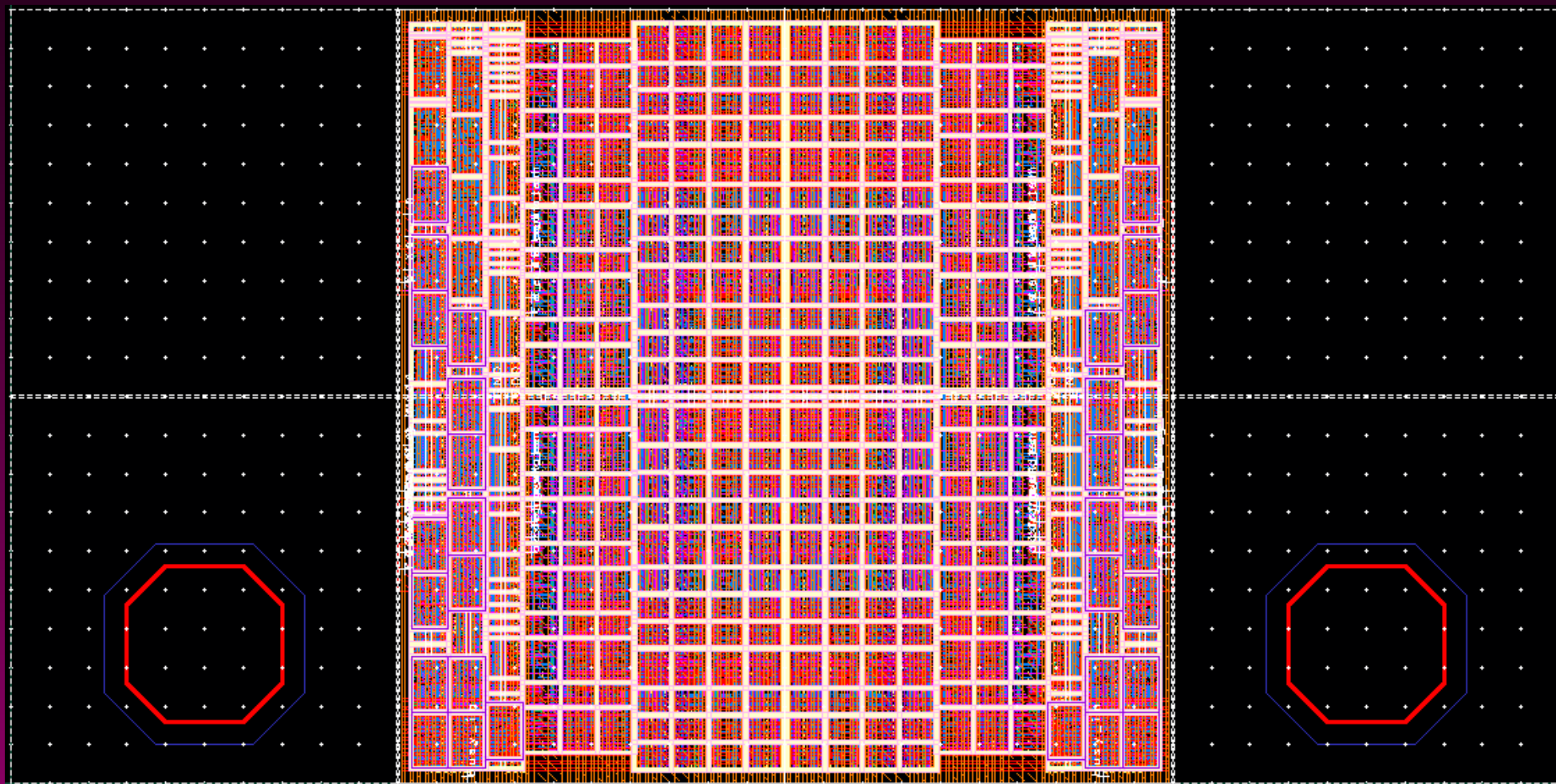




Double pixel

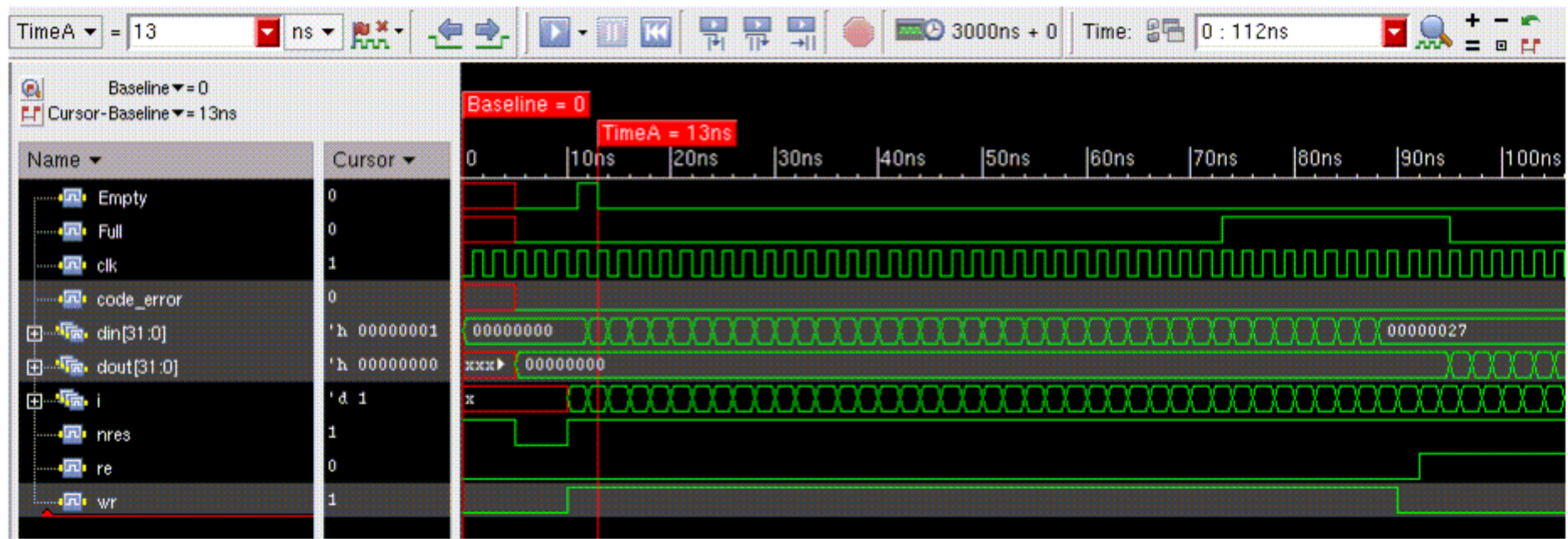


Sezione di Torino



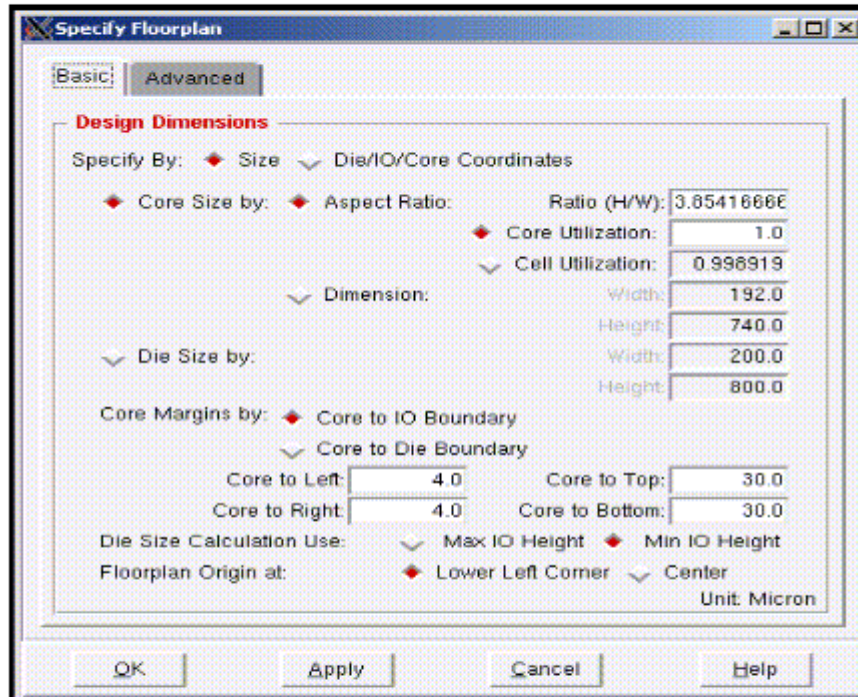
32x32 FIFO:

1. Hamming code encoder/decoder for single error correction (SEC)
2. Triple Module Redundancy registers for FIFO control logic;
3. Triple Module Redundancy Flip-Flops for counters;



L. Toscano

Routing layers = 5



Density: 72.964%

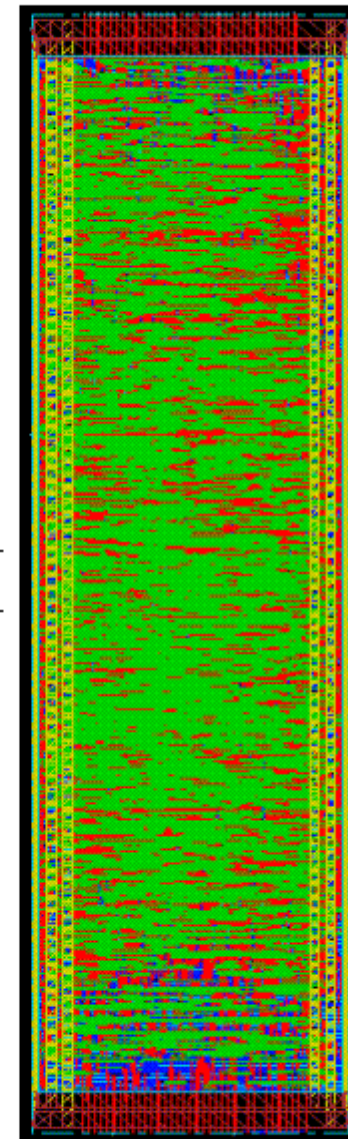
average power: 14.570 mW

average switching: 12.580e mW

average leakage power: 1.9895 mW

worst IR drop average analysis: 3.4679 mV

Data in



clk
rst

Data out

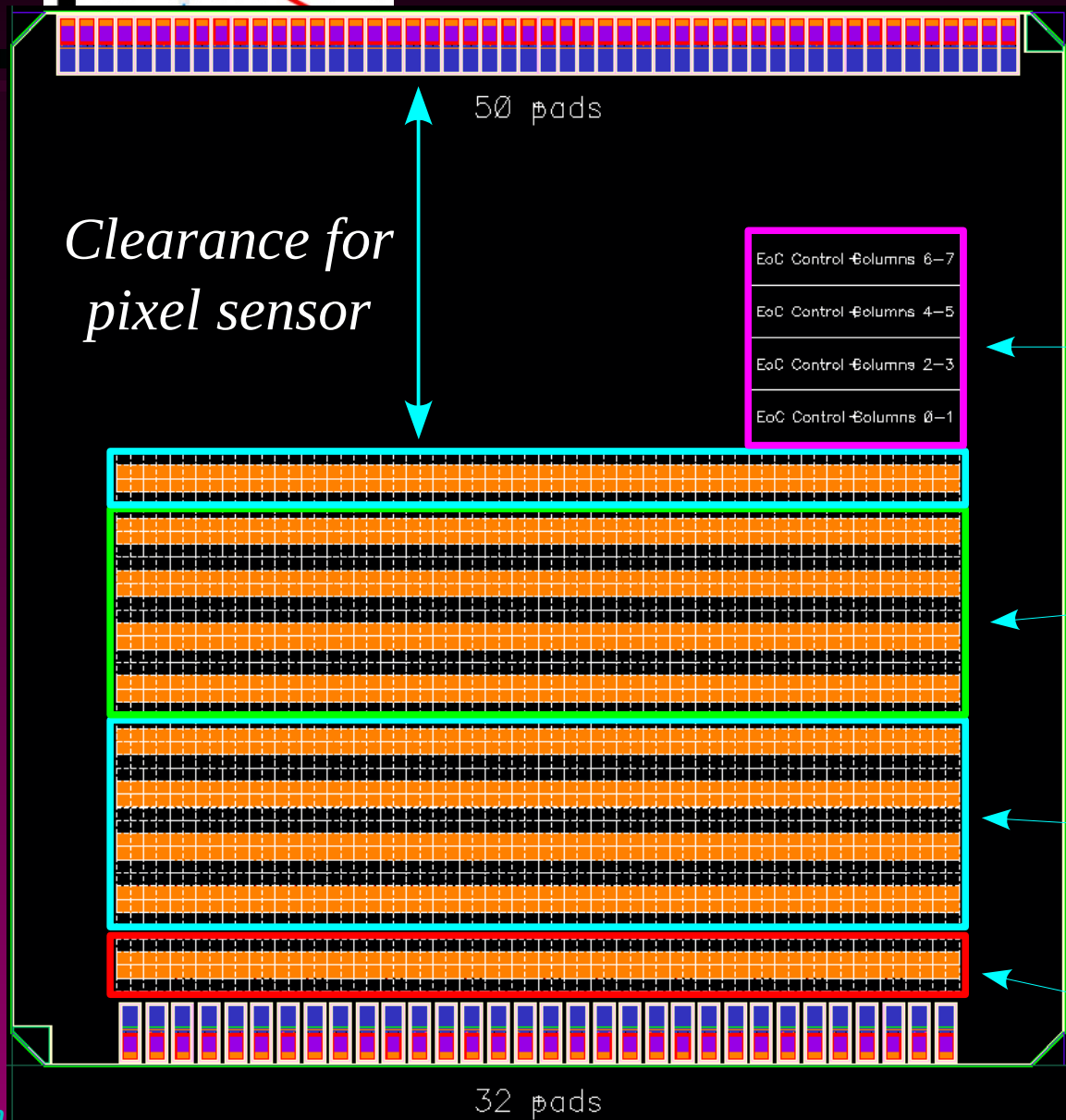
L. Toscano



Floorplan



Sezione di Torino



End of column FIFOs

32x2 pixel column

128x2 pixel column

128x2 pixel column

32x2 pixel column *or*
32 channels strips r/o



Design status



Sezione di Torino

- * Analogue pixel circuitry modification completed, layout design ongoing.
- * Digital pixel section layout well advanced.
- * HDL system simulation re-started.
- * 160 MHz column drivers and receivers test ok (*NA62 GtkTo*).
- * Hamming protected FIFO layout completed.
- * End of column control logic design started.
- * Slow control interface design to be started.
- * E-link interface under test at CERN.

Radiation Hard Optical Link Architecture

Defined in the "DG White Paper"

■ "Work Package 3-1"

- Objective:
 - Development of an high speed bidirectional radiation hard optical link
- Deliverable:
 - Tested and qualified radiation hard optical link
- Duration:
 - 4 years (2008 - 2011)

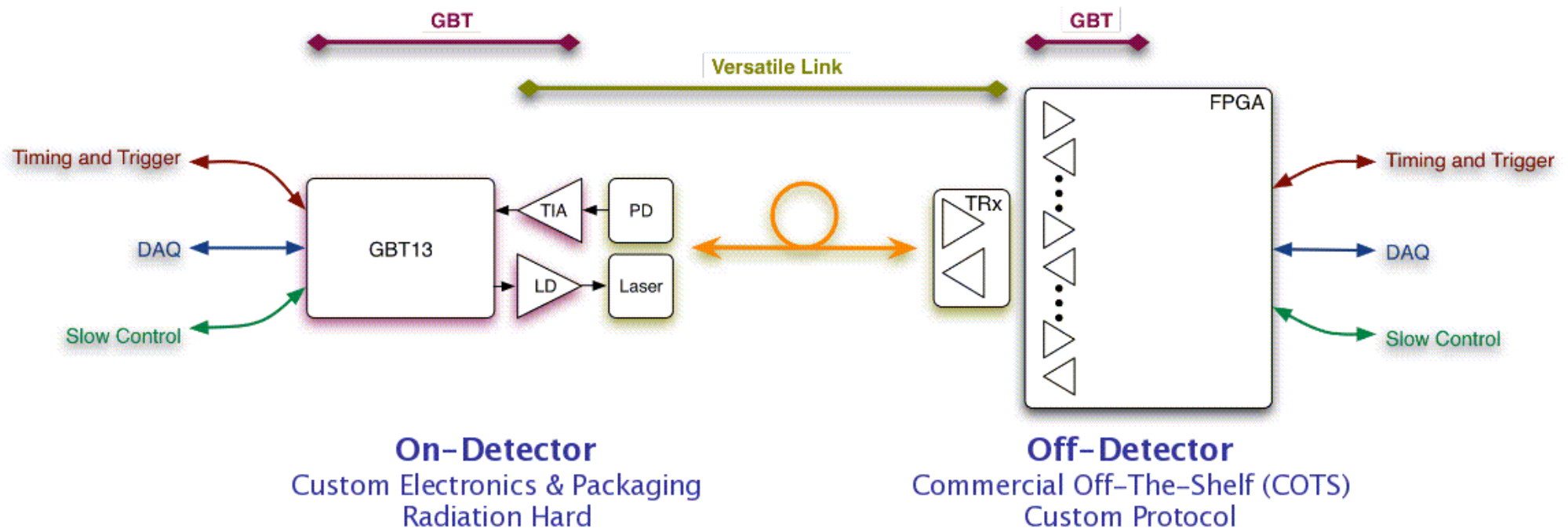
Radiation Hard Optical Link:

■ Versatile link project:

- Opto-electronics
- Radiation hardness
- Functionality testing
- Packaging

■ GBT project:

- ASIC design
- Verification
- Functionality testing
- Packaging



Project Schedule

■ 2008

- Design and prototyping of performance critical building blocks:
 - GBTIA, GBLD, Serializer, De-Serializer, Phase Shifter
- First tests of optoelectronics components
 - SEU tests on PIN receivers
- Proceed with the link specification meetings
- General link specification

■ 2009

- Design/prototype/test of basic serializer/de-serializer (GBT-SERDES) chip
 - GBT-SERDES ("Tape-out" 9th of November)
- Design/prototype/test of optoelectronics packaging
 - GBTIA + PIN on TO CAN

■ 2010

- GBLD re-spin
- GBT-SERDES testing ← !
- Detailed link specification document
- Full prototype of optoelectronics packaging
- Prototype of "complete" GBTX chip } ?

■ 2011

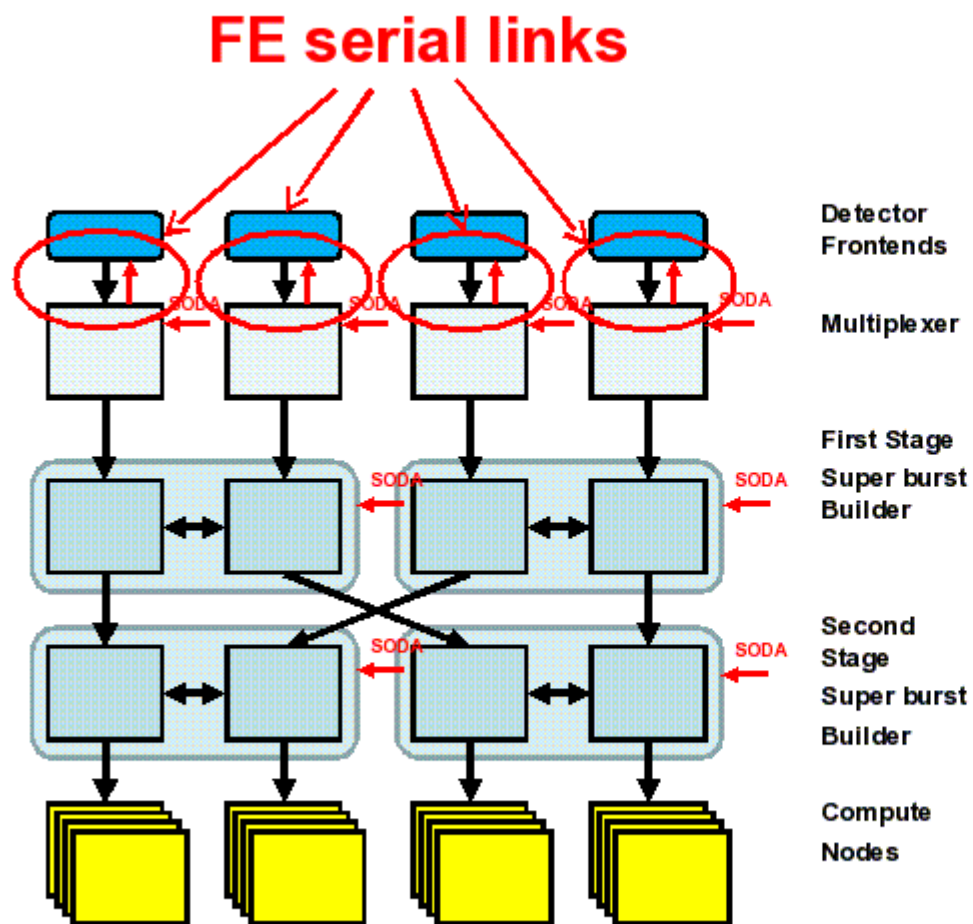
- Extensive test and qualification of full link prototypes
- System demonstrator (s) with use of full link
- Schedule of the final production version is strongly dependent on the evolution of the LHC upgrade schedule



PANDA DAQ



Sezione di Torino



DAQ :

Beam structure : 2 μ s burst + 400 ns pause

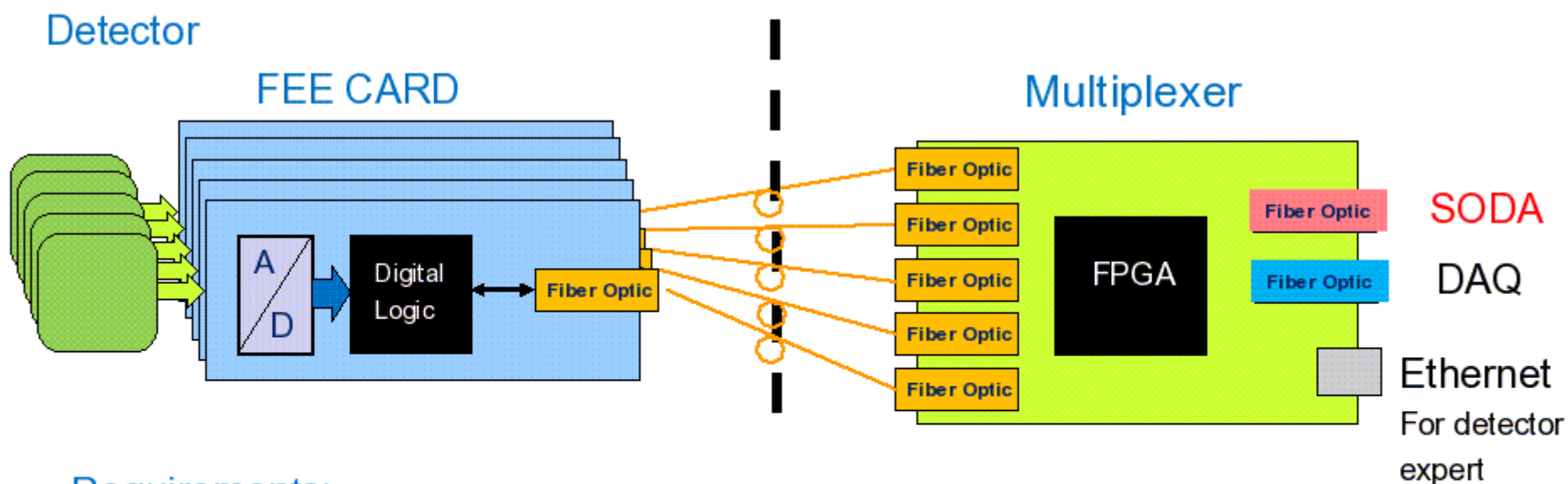
Super burst : 256 bursts $\rightarrow$ 614.4 μ s

Data block corresponds to one burst

Superblock corresponds to 614.4 μ s beam

DAQ builds super bursts by Round Robin algorithm

200 GB/s sustained data rate



Requirements:

FEE interface functionality:

- SODA commands
- DATA transmission
- Slow control

Speed: 1.5-4.5Gb/s

Some detectors require radiation tolerant components

Hardware solution: FPGA with SerDes

Resource usage

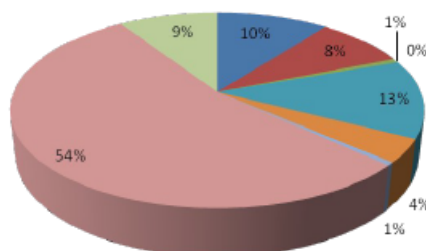
- Implementing several channels leads to an important usage of logic cells resources

Max usable/available nb of channel	Altera Stratix II GX	Logic cells usage in %
8/8	EP2SGX30D	92%
12/12	EP2SGX60D	78%
16/16	EP2SGX90E	69%
20/20	EP2SGX130G	59%
24/24		

Max usable/available nb of channel	Xilinx Virtex 5	Logic cells usage in %
3/8	XC5VFX30T	87%
10/16	XC5VFX100T	93%
13/20	XC5VFX130T	94%
20/24	XC5VFX200T	96%

This table gives only resource usage in terms of logic cells but other resources are used such as DSP blocks or RAM. Differences between Altera and Xilinx logic cells usage can be explained by the different policies they adopt in term of ratio between number of logic cells and number of transceivers.

- The Reed Solomon decoder takes most of the resources



Resource usage (in ALMs*) by entity for one full channel implemented on Stratix II GX

ALM: Adaptive Logic Module (contains 2LUTs and 2 registers)

■ scramble ■ encoding ■ mux ■ GX_serdes ■ manual frame align ■ patternsearch ■ demux ■ decoding ■ descramble



Conclusions



Sezione di Torino

- * ToPiX :
 - * Pixel cell design well advanced, complete layout will be finalized in the summer
 - * HDL system simulations restarted
 - * End of column design ongoing
 - ➔ *On track for the November submission (up to now...)*
- * Data transmission :
 - * E-link interface for the current prototype
 - * GBT tests ongoing at CERN
- * Future steps :
 - * ToPiX version 3 submission and tests
 - * ToPiX v3 – detector and ToPiX v3 – GBT tests
 - * GBT-FPGA customization for PANDA (interface with SODA and DAQ)